

SOT851-3

plastic, heatsink small outline package; 36 leads; low stand-off-height

Package information

Package summary 1

Terminal position code D (double) HSOP36 Package type descriptive code Package type industry code HSOP36

Package style descriptive code HSOP (heatsink small outline package)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 05-11-2018 Manufacturer package code SOT851

Table 1. Package summary

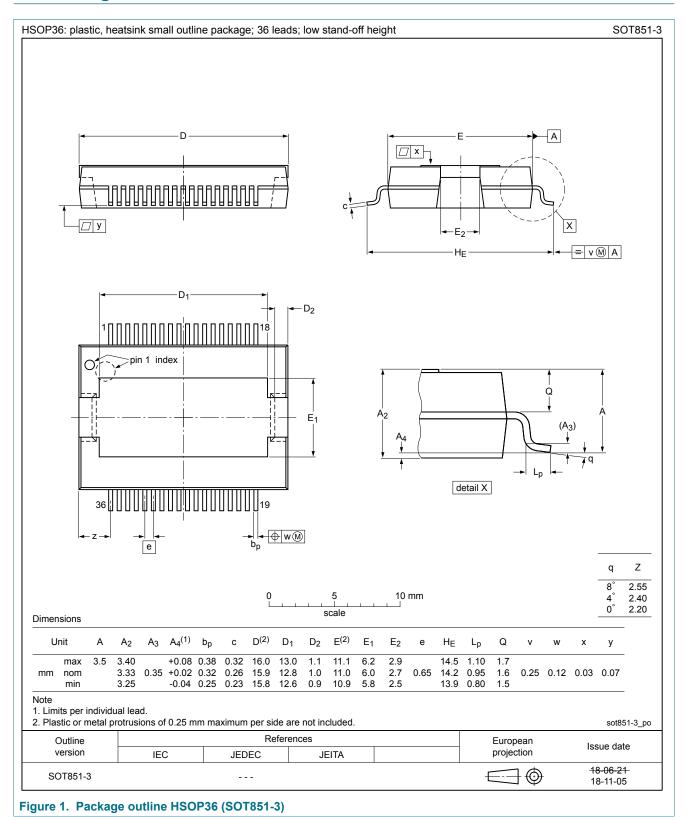
Parameter	Min	Nom	Max	Unit
package length	15.8	15.9	16	mm
package width	10.9	11	11.1	mm
seated height	-	-	3.5	mm
package height	3.25	3.33	3.4	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	36	-	



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2 Package outline



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3 Legal information

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